

P²SI[®] DS77 is a 500-550°F (260-288°C) service temperature structural adhesive with a versatile cure temperature range of 620°F (327°C) to 700°F (371°C). P²SI[®] DS77 is well suited for bonding wide areas. It is also compatible with PMR-15, Avimid[®] R, RP46, and Avimid[®] RB, as it can be fully cured at lower temperatures than P²SI[®] DS6N. P²SI[®] DS77 is thermosetting, does not contain MDA, and the only volatiles are ethanol and water. P²SI[®] DS77 is available in a paste form or a film prepreg. P²SI[®] DS77 film has very good tack and drape properties.

Surface Preparation

For composite laminate surface preparation, we recommend grit blasting both bonding surfaces with 50 µm alumina grit, followed by washing with soapy water (typical dish detergent), washing with distilled water, rinsing with ACS certified acetone, and drying at 230°F (110°C) for 4-8 hours prior to bonding. For metal surface preparation, please contact P²SI to discuss your application. P²SI[®] N18G primer may be required for bonding certain metallic surfaces.

Supported Film Adhesive Properties

Property	Value	Test Method
Overlap Shear Strength, psi (MPa)		ASTM D5868
75°F (23°C)	2700 (19)	
550°F (288°C)	1600 (11)	
Aging: 550°F (288°C) / 1000h		
75°F (23°C)	1600 (11)	
500°F (260°C)	1800 (13)	
Aging: Moisture Saturated		
500°F (260°C)	1400 (10)	
In-Plane Shear Strength, psi (MPa)		ASTM D3846
75°F (23°C)	4600 (32)	
550°F (288°C)	2200 (15)	
Aging: 550°F (288°C) / 1000h		
550°F (288°C)	2500 (17)	
Aging: Moisture Saturated		
75°F (23°C)	3500 (24)	
500°F (260°C)	1700 (12)	

IMPORTANT NOTICE:

The information and statements herein are, we believe, to be reliable but are not construed as a warranty, expressed or implied, or any other representation for which Performance Polymer Solutions Inc. (P²SI) assumes legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for a particular use of the products referred to herein. NO WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE IS MADE. Nothing herein is to be taken as permission, or recommendation to practice any patent invention without an appropriate license.